

PRODUCT ADVANTAGE

- High Reliability
- Increase Throughput
- 5X Reflow Cycles
- Simplify Assembly Process
- Low and High Temperature Curing Options
- Filled & Unfilled Options
- Good For Miniaturization

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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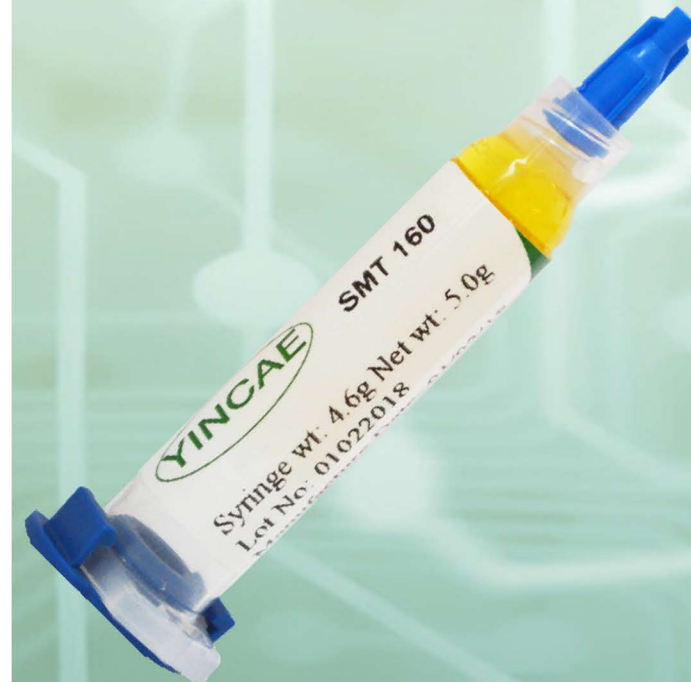
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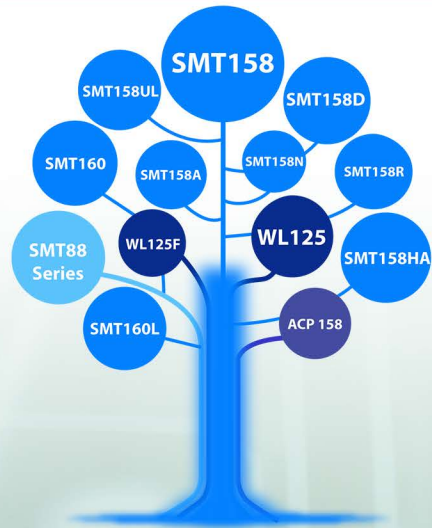
INNOVATION AT ITS BEST



YINCAE
Reflowable Underfills
SMT 160 Series

*Preferred by global leaders in the
electronics manufacturing industry*

YINCAE® SMT 160 Series Underfills



YINCAE® has recently developed a reflowable (no - flow) underfill: SMT 160. This material is designed to eliminate capillary underfill, simplify the assembly process, combine soldering and underfilling in SMT processes, and increase throughput.

Reflowable underfills are dispensed or printed onto the board before component placement occurs. The design of the material allow it to remain in place so that component placement can occur in a subsequent step.

These materials are especially helpful for applications with a narrow footprint.

YINCAE Reflowable Underfill Materials

SMT 160 - unfilled, dispenseable and printable, compatible with standard Pb-free reflow temperatures

SMT 160L - unfilled, dispenseable and printable, designed for low temperature (140 - 170°C) curing

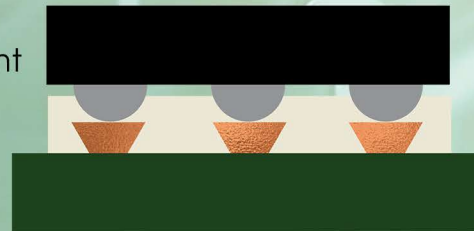
SMT 158R - filled, dispenseable and printable, designed for applications with large C.T.E. mismatch

SMT 160 Application Process

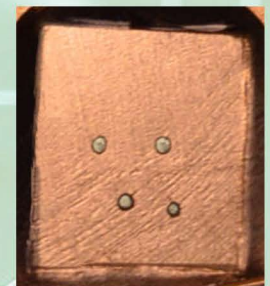
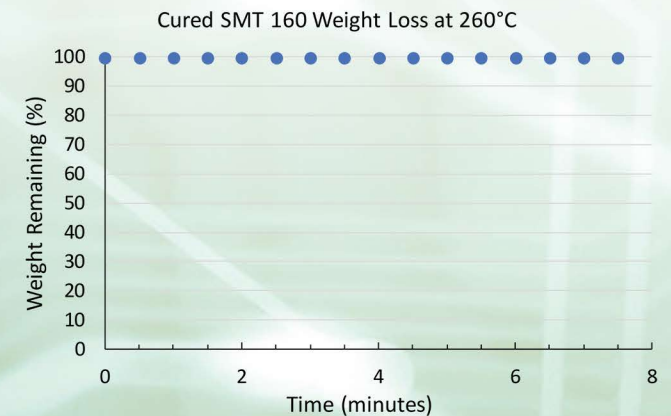
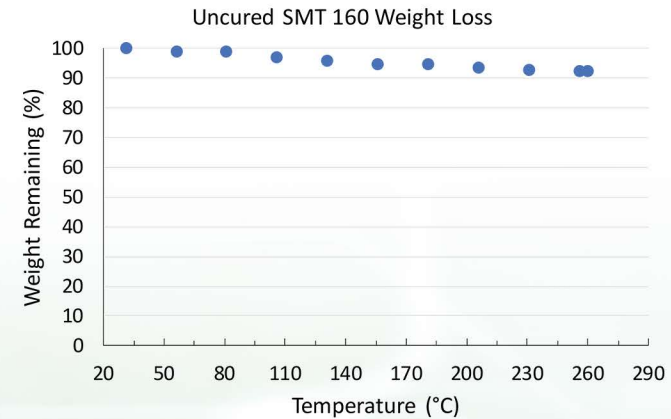
Print



Place Component



After Reflow



SMT 160 is a void free underfill and exhibits no slump when printed